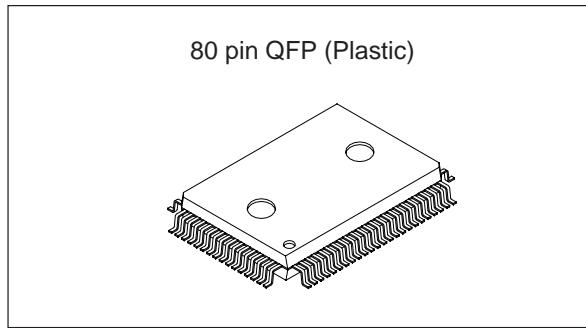


CMOS 8-bit Single Chip Microcomputer**Description**

The CXP84120/84124 is a CMOS 8-bit single chip micro-computer integrating on a single chip an A/D converter, serial interface, timer/counter, time base timer, capture timer/counter, remote control reception circuit and other servo systems besides the basic configurations of 8-bit CPU, ROM, RAM, and I/O port.

The CXP84120/84124 also provides a power-on reset function and a sleep/stop function that enables lower power consumption.

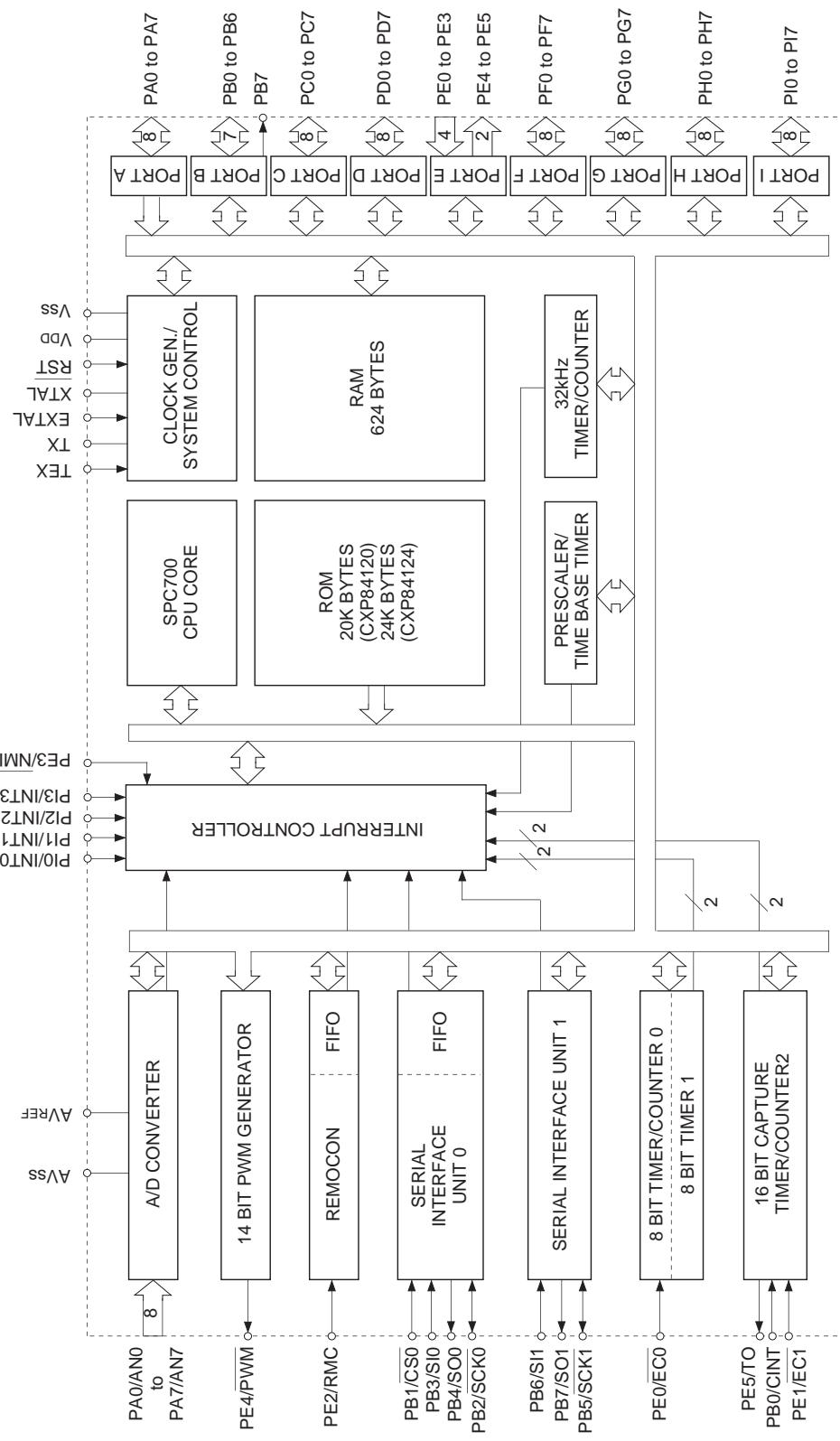
**Features**

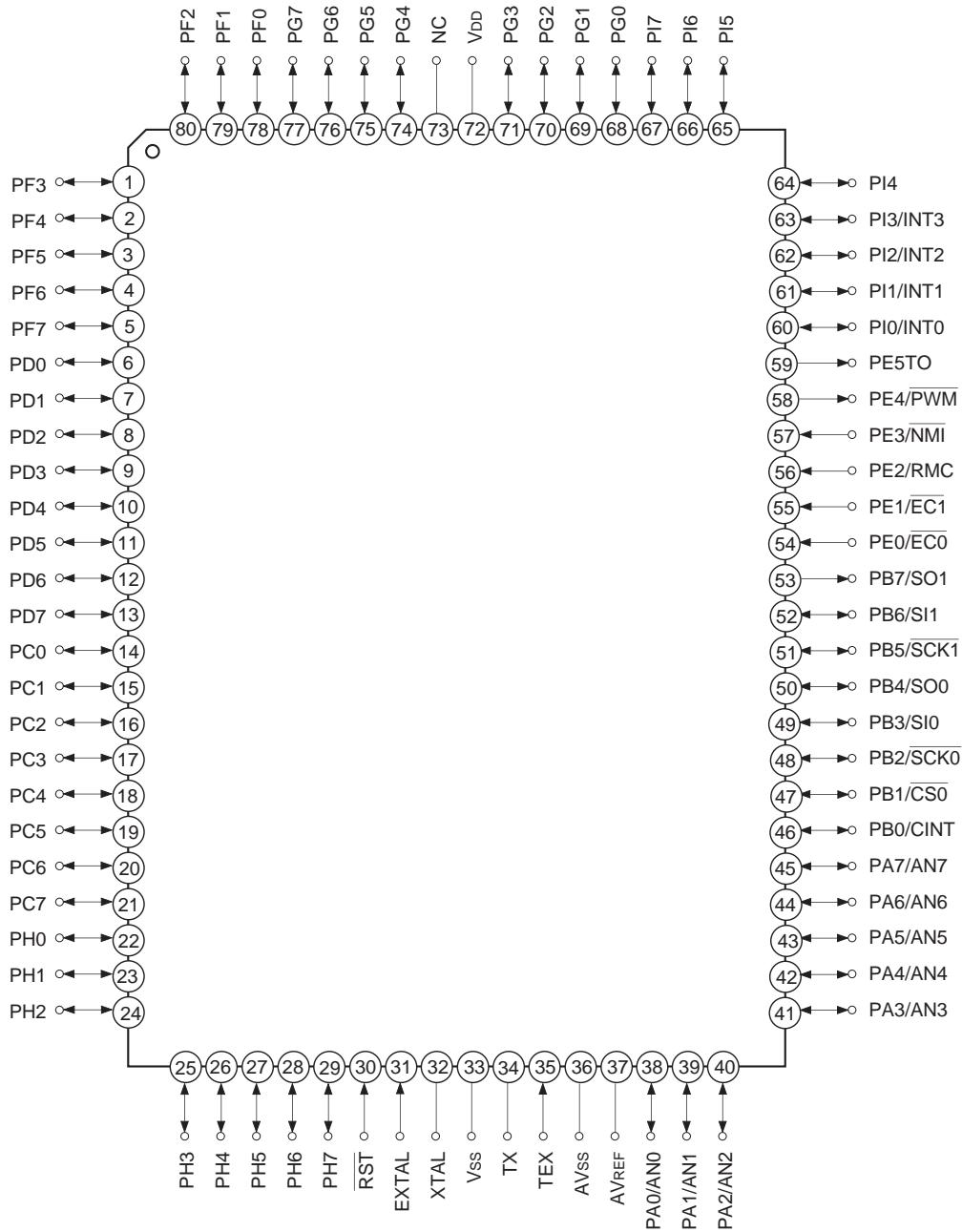
- Wide-range instruction system (213 instructions) to cover various types of data
 - 16-bit arithmetic/multiplication and division/Boolean bit operation instructions
- Minimum instruction cycle 400ns at 10MHz operation
 122µs at 32kHz operation
- Incorporated ROM capacity 20K bytes (CXP84120)
 24K bytes (CXP84124)
- Incorporated RAM capacity 624 bytes
- Peripheral functions
 - A/D converter 8 bits, 8 channels, successive approximation method
(Conversion time of 32µs/10MHz)
 - Serial interface SIO with 8-bit, 8-stage FIFO incorporated for data use
(Auto transfer for 1 to 8 bytes), 1 channel
 8-bit standard SIO, 1 channel
 - Timer 8-bit timer
 8-bit timer/counter
 19-bit time base timer
 16-bit capture timer/counter
 32kHz timer/counter
 - Remote control reception circuit Incorporated noise elimination circuit
 Incorporated 8-bit, 6-stage FIFO for measurement data
 - PWM output 14 bits, 1 channel
- Interruption 14 factors, 15 vectors, multi-interruption possible
- Standby mode Sleep/stop
- Package 80-pin plastic QFP
- Piggyback/evaluation chip CXP84100 80-pin ceramic QFP

Structure

Silicon gate CMOS IC

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Block Diagram

Pin Assignment (Top View)

Note) NC (Pin 73) must be connected to VDD.

Pin Description

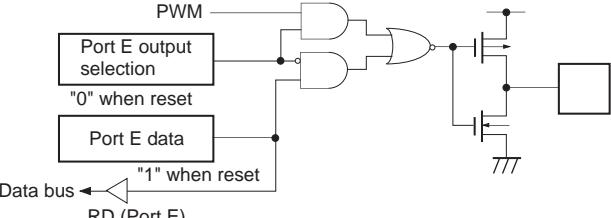
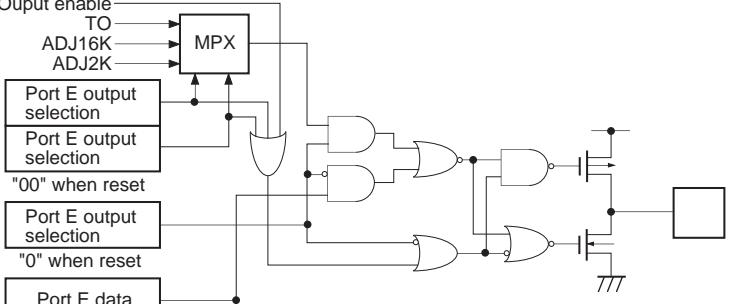
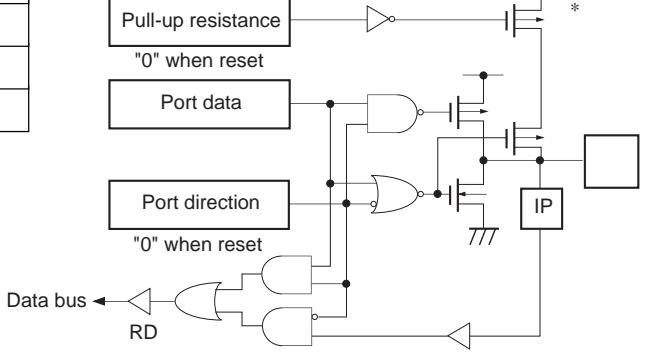
Symbol	I/O	Description	
PA0/AN0 to PA7/AN7	I/O/Analog input	(Port A) 8-bit I/O port. I/O can be set in a unit of single bit. Incorporation of the pull-up resistance can be set through the software in a unit of 4 bits. (8 pins)	Analog inputs to A/D converter. (8 pins)
PB0/CINT	I/O/Input	(Port B)	External capture input to 16-bit timer/counter.
PB1/CS0	I/O/Input		Chip select input for serial interface (CH0).
PB2/SCK0	I/O/I/O		Serial clock I/O (CH0).
PB3/SI0	I/O/Input		Serial data input (CH0).
PB4/SO0	I/O/Output		Serial data output (CH0).
PB5/SCK1	I/O/I/O		Serial clock I/O (CH1).
PB6/SI1	I/O/Input		Serial data input (CH1).
PB7/SO1	Output/Output		Serial data output (CH1).
PC0 to PC7	I/O	(Port C) 8-bit I/O port. I/O can be set in a unit of single bit. Capable of driving 12mA sink current. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PD0 to PD7	I/O	(Port D) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	
PE0/EC0	Input/Input	(Port E) 6-bit port. Lower 4 bits are for inputs; upper 2 bits are for outputs. (6 pins)	External event inputs for timer/counter. (2 pins)
PE1/EC1	Input/Input		Remote control reception circuit input.
PE2/RMC	Input/Input		Non-maskable interruption request input.
PE3/NMI	Input/Input		14-bit PWM output.
PE4/PWM	Output/Output		Rectangular wave output for 16-bit timer/counter. Output for 32kHz oscillation frequency division.
PE5/TO/ADJ	Output/Output/ Output		
PF0 to PF7	I/O	(Port F) 8-bit I/O port. I/O can be set in a unit of single bit. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	

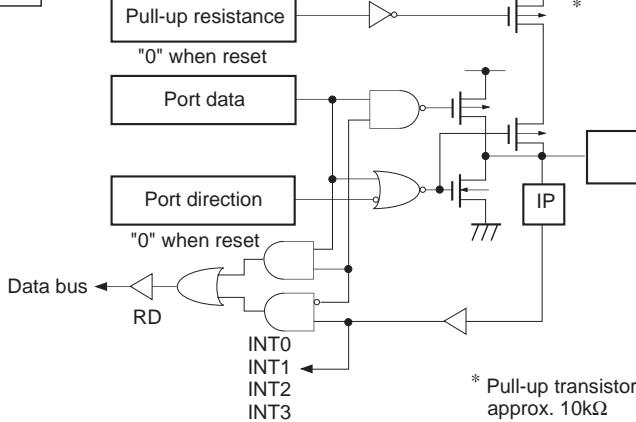
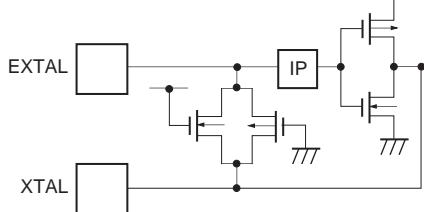
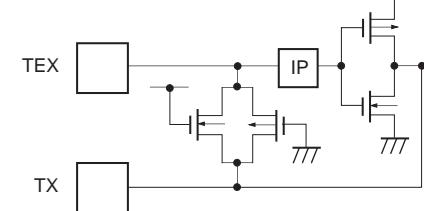
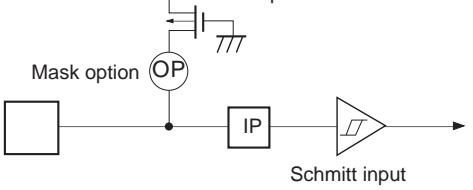
Symbol	I/O	Description		
PG0 to PG7	I/O	(Port G) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)		
PH0 to PH7	I/O	(Port H) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)		
PI0/INT0 to PI3/INT3	I/O/Input	(Port I) 8-bit I/O ports. I/O can be set in a unit of single bit. Incorporation of pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	External interruption request inputs.	
PI4 to PI7				
EXTAL	Input	Crystal connectors for system clock oscillation. When the clock is supplied externally, input to EXTAL; opposite phase clock should be input to XTAL.		
XTAL	Output			
TEX	Input	Crystal connectors for 32kHz timer/counter clock generation circuit. Connect a 32kHz crystal oscillator between TEX and TX. For usage as event input, connect clock oscillation source to TEX, and open TX.		
TX	Output			
<u>RST</u>	Input	Low-level active, system reset.		
NC		NC. Under normal operating conditions, connect to VDD.		
AVREF	Input	Reference voltage input for A/D converter.		
AVss		A/D converter GND.		
VDD		Positive power supply.		
Vss		GND		

Input/Output Circuit Formats for Pins

Pin	Circuit format	When reset
PA0/AN0 to PA7/AN7 8 pins	<p>Port A</p> <p>Pull-up resistance "0" when reset</p> <p>Port A data</p> <p>Port A direction "0" when reset</p> <p>Data bus</p> <p>RD (Port A)</p> <p>Port A input selection "0" when reset</p> <p>Input multiplexer</p> <p>A/D converter</p> <p>IP</p> <p>Input protection circuit</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB0/CINT PB1/CS0 PB3/SI0 PB6/SI1 4 pins	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>CINT CS0 SI0 SI1</p> <p>Schmitt input</p> <p>IP</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB2/SCK0 PB5/SCK1 2 pins	<p>Port B</p> <p>Pull-up resistance "0" when reset</p> <p>SCK OUT</p> <p>Output enable</p> <p>Port B output selection "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>SCK in</p> <p>IP</p> <p>Schmitt input</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z

Pin	Circuit format	When reset
PB4/SO0 1 pin	<p>Port B</p> <p>Pull-up resistance</p> <p>SO</p> <p>Output enable</p> <p>Port B output selection "0" when reset</p> <p>Port B data</p> <p>Port B direction "0" when reset</p> <p>Data bus</p> <p>RD (Port B)</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
PB7/SO1 1 pin	<p>Port B</p> <p>Internal reset signal</p> <p>SO</p> <p>Output enable</p> <p>Port B output selection "1" when reset</p> <p>Port B data</p> <p>Data bus</p> <p>RD (Port B)</p> <p>* Pull-up transistors approx. 10kΩ</p>	High level
PC0 to PC7 8 pins	<p>Port C</p> <p>Pull-up resistance "0" when reset</p> <p>Port C data</p> <p>Port C direction "0" when reset</p> <p>Data bus</p> <p>RD (Port C)</p> <p>*1 Large current drive of 12mA possible *2 Pull-up transistors approx. 10kΩ</p>	Hi-Z
PE0/ <u>EC0</u> PE1/EC1 PE2/RMC PE3/NMI 4 pins	<p>Port E</p> <p>Schmitt input</p> <p>IP</p> <p>EC0 EC1 RMC/NMI</p> <p>Data bus</p> <p>RD (Port E)</p>	Hi-Z

Pin	Circuit format	When reset
PE4/PWM 1 pin	<p>Port E</p>  <p>Port E output selection "0" when reset Port E data "1" when reset</p> <p>PWM</p> <p>Data bus → RD (Port E)</p>	High level
PE5/TO/ADJ 1 pin	<p>Port E</p>  <p>Output enable TO ADJ16K ADJ2K Port E output selection Port E output selection "00" when reset Port E output selection "0" when reset Port E data "1" when reset</p> <p>Data bus ← RD (Port E)</p> <p>* ADJ signals are frequency division outputs for 32kHz oscillation frequency adjustment. ADJ2K provides usage as buzzer output.</p>	High level
PD0 to PD7 PF0 to PF7 PG0 to PG7 PH0 to PH7 PI4 to PI7 36 pins	<p>Port D Port F Port G Port H Port I</p>  <p>Pull-up resistance "0" when reset Port data Port direction "0" when reset</p> <p>Data bus ← RD</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z

Pin	Circuit format	When reset
PIO/INT0 to PI3/INT3 4 pins	 <p>Port I</p> <p>Pull-up resistance "0" when reset</p> <p>Port data</p> <p>Port direction "0" when reset</p> <p>Data bus RD</p> <p>INT0 INT1 INT2 INT3</p> <p>* Pull-up transistors approx. 10kΩ</p>	Hi-Z
EXTAL XTAL 2 pins	 <ul style="list-style-type: none"> Diagram shows circuit composition during oscillation. Feedback resistor is removed during stop. 	Oscillation
TEX TX 2 pins	 <ul style="list-style-type: none"> Diagram shows circuit composition during oscillation. When the operation of the oscillation circuit is stopped by the software, the feedback resistor is removed, and TEX and TX become "Low" level and "High" level respectively. 	Oscillation
<u>RST</u> 1 pin	 <p>Pull-up resistor</p> <p>Mask option OP</p> <p>Schmitt input</p>	Low level

Absolute Maximum Ratings

(Vss = 0V reference)

Item	Symbol	Rating	Unit	Remarks
Supply voltage	VDD	-0.3 to +7.0	V	
	AVss	-0.3 to +0.3	V	
Input voltage	VIN	-0.3 to +7.0*1	V	
Output voltage	VOUT	-0.3 to +7.0*1	V	
High level output current	IOH	-5	mA	Output per pin
High level total output current	Σ IOH	-50	mA	Total for all output pins
Low level output current	iol	15	mA	Value per pin, excluding large current outputs
	iolc	20	mA	Value per pin*2 for large current outputs
Low level total output current	Σ iol	100	mA	Total for all output pins
Operating temperature	Topr	-20 to +75	°C	
Storage temperature	Tstg	-55 to +150	°C	
Allowable power dissipation	PD	600	mW	

*1 VIN and VOUT must not exceed VDD + 0.3V.

*2 The large current drive transistor is the N-ch transistor of Port C (PC).

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should be conducted under the recommended operating conditions. Exceeding these conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions

(Vss = 0V reference)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	VDD	4.5	5.5	V	High-speed mode guaranteed operation range*1
		3.5	5.5		Low-speed mode guaranteed operation range*1
		2.7	5.5		Guaranteed operation range with TEX clock
		2.5	5.5		Guaranteed data hold range during stop
High level input voltage	VIH	0.7VDD	VDD	V	*2
	VIHS	0.8VDD	VDD	V	Hysteresis input*3
	VIHEX	VDD - 0.4	VDD + 0.3	V	EXTAL*4
Low level input voltage	VIL	0	0.3VDD	V	*2
	VILS	0	0.2VDD	V	Hysteresis input*3
	VILEX	-0.3	0.4	V	EXTAL*4
Operating temperature	Topr	-20	+75	°C	

*1 High-speed mode is 1/2 frequency division clock selection; low-speed mode is 1/16 frequency division clock selection.

*2 Value for each pin of normal input ports (PA, PB3, PB4, PB6, PC, PD, PF to PH, PI4 to PI7).

*3 Value of the following pins: \overline{RST} , CINT, $\overline{CS0}$, $\overline{SCK0}$, $\overline{SCK1}$, $\overline{EC0}$, $\overline{EC1}$, RMC, \overline{NMI} , INT0, INT1, INT2, INT3.

*4 Specifies only during external clock input.

Electrical Characteristics**DC Characteristics**

(Ta = -20 to +75°C, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
High level output voltage	V _{OH}	PA to PD, PE4, PE5, PF to PI	V _{DD} = 4.5V, I _{OH} = -0.5mA	4.0			V
			V _{DD} = 4.5V, I _{OH} = -1.2mA	3.5			V
Low level output voltage	V _{OL}	V _{DD} = 4.5V, I _{OL} = 1.8mA			0.4		V
			V _{DD} = 4.5V, I _{OL} = 3.6mA			0.6	V
	PC	V _{DD} = 4.5V, I _{OL} = 12.0mA				1.5	V
Input current	I _{IHE}	EXTAL	V _{DD} = 5.5V, V _{IH} = 5.5V	0.5		40	μA
	I _{IIE}		V _{DD} = 5.5V, V _{IL} = 0.4V	-0.5		-40	μA
	I _{IHT}	TEX	V _{DD} = 5.5V, V _{IH} = 5.5V	0.1		10	μA
	I _{ILT}			-0.1		-10	μA
	I _{IIR}	RST ^{*1}	V _{DD} = 5.5V, V _{IL} = 0.4V	-1.5		-400	μA
	I _{IL}	PA to PD ^{*2} , PF to PI ^{*2}				-2.0	mA
			V _{DD} = 4.5V, V _{IL} = 4.0V	-10			μA
I/O leakage current	I _{Iz}	P _{E0} to P _{E3} , RST ^{*1}	V _{DD} = 5.5V, V _I = 0, 5.5V			±10	μA
Power supply current ^{*3}	I _{DD1}	V _{DD}	High-speed mode operation (1/2 frequency division clock)		18	40	mA
	I _{DD2}		V _{DD} = 5.5V, 10MHz crystal oscillation (C ₁ = C ₂ = 15pF)		35	100	μA
	I _{DD3}		V _{DD} = 3V, 32kHz crystal oscillation (C ₁ = C ₂ = 47pF)		1.1	8	mA
	I _{DD4}	V _{DD}	Sleep mode				
	I _{DD5}		V _{DD} = 5.5V, 10MHz crystal oscillation (C ₁ = C ₂ = 15pF)				
	I _{DD6}	V _{DD}	V _{DD} = 3V, 32kHz crystal oscillation (C ₁ = C ₂ = 47pF)		9	30	μA
	I _{DD7}		Stop mode			10	μA
			V _{DD} = 5.5V, termination of 10MHz and 32kHz crystal oscillation				
Input capacity	C _{IN}	Pins other than PB7, PE4, PE5, AV _{REF} , AV _{SS} , V _{DD} , V _{SS}	Clock 1MHz 0V for all pins excluding measured pins		10	20	pF

*1 RST specifies the input current when pull-up resistance has been selected; leakage current when no resistance has been selected.

*2 Pins PA to PD, and PF to PI specify the input current when pull-up resistance has been selected; leakage current when no resistance has been selected. (Excludes output PB7)

*3 When all pins are open.

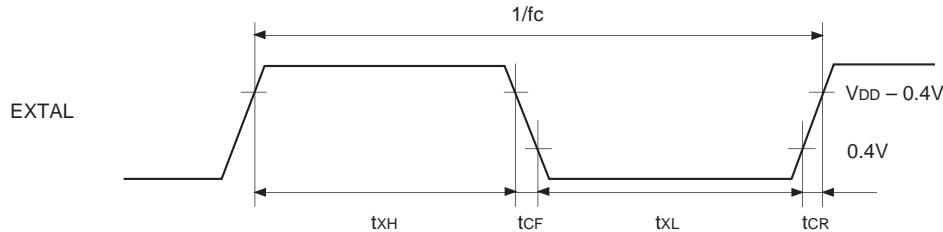
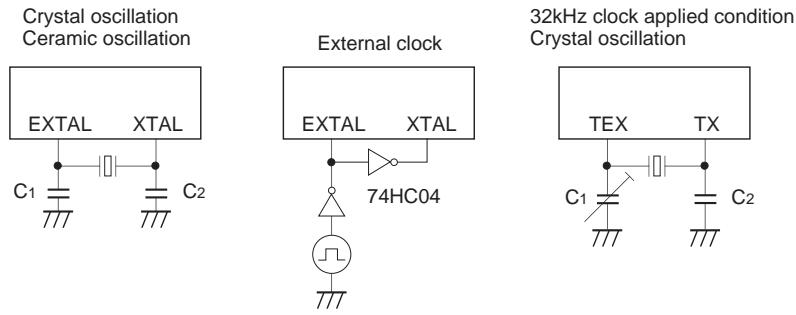
AC Characteristics**(1) Clock timing**

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, Vss = 0V reference)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
System clock frequency	fc	XTAL EXTAL	Fig. 1, Fig. 2	1		10	MHz
System clock input pulse width	t _{XL} , t _{XH}	EXTAL	Fig. 1, Fig. 2 External clock drive	37.5			ns
System clock input rise time, fall time	t _{CR} , t _{CF}	EXTAL	Fig. 1, Fig. 2 External clock drive			200	ns
Event count input clock pulse width	t _{EH} , t _{EL}	<u>EC0</u> <u>EC1</u>	Fig. 3	tsys + 50*1			ns
Event count input clock rise time, fall time	t _{ER} , t _{EF}	<u>EC0</u> <u>EC1</u>	Fig. 3			20	ms
System clock frequency	fc	TEX TX	V _{DD} = 2.7 to 5.5V Fig. 2 (32kHz clock applied condition)		32.768		kHz
Event count input clock input pulse width	t _{TL} , t _{TH}	TEX	Fig. 3	10			μs
Event count input clock rise time, fall time	t _{TR} , t _{TF}	TEX	Fig. 3			20	ms

*1 tsys indicates the three values below according to the upper two bits (CPU clock selection) of the clock control register (address: 00FEH).

tsys [ns] = 2000/fc (upper two bits = "00"), 4000/fc (upper two bits = "01"), 16000/fc (upper two bits = "11")

**Fig. 1. Clock timing****Fig. 2. Clock applied conditions**

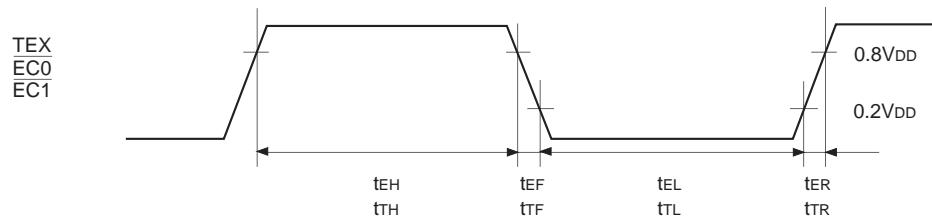


Fig. 3. Event count clock timing

(2) Serial transfer (CH0)

(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V reference)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CS0 ↓ → SCK0 delay time	t _{DCSK}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↑ → SCK0 float delay time	t _{DCSKF}	SCK0	Chip select transfer mode (SCK0 = output mode)		t _{sys} + 200	ns
CS0 ↓ → SO0 delay time	t _{DCSO}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 ↑ → SO0 float delay time	t _{DCSOF}	SO0	Chip select transfer mode		t _{sys} + 200	ns
CS0 High level width	t _{WHCS}	CS0	Chip select transfer mode	t _{sys} + 200		ns
SCK0 cycle time	t _{KCY}	SCK0	Input mode	2t _{sys} + 200		ns
			Output mode	16000/fc		ns
SCK0 High, Low level width	t _{KH} , t _{KL}	SCK0	Input mode	t _{sys} + 100		ns
			Output mode	8000/fc - 50		ns
SI0 input setup time (for SCK0 ↑)	t _{SIK}	SI0	SCK0 input mode	100		ns
			SCK0 output mode	200		ns
SI0 input hold time (for SCK0 ↑)	t _{KSI}	SI0	SCK0 input mode	t _{sys} + 200		ns
			SCK0 output mode	100		ns
SCK0 ↓ → SO0 delay time	t _{KSO}	SO0	SCK0 input mode		t _{sys} + 200	ns
			SCK0 output mode		100	ns

Note 1) t_{sys} indicates the three values below according to the upper two bits (CPU clock selection) of the clock control register (address: 00FEH).

t_{sys} [ns] = 2000/fc (upper two bits = "00"), 4000/fc (upper two bits = "01"), 16000/fc (upper two bits = "11")

Note 2) The load condition for the SCK0 output mode, SO0 output delay time is 50pF + 1TTL.

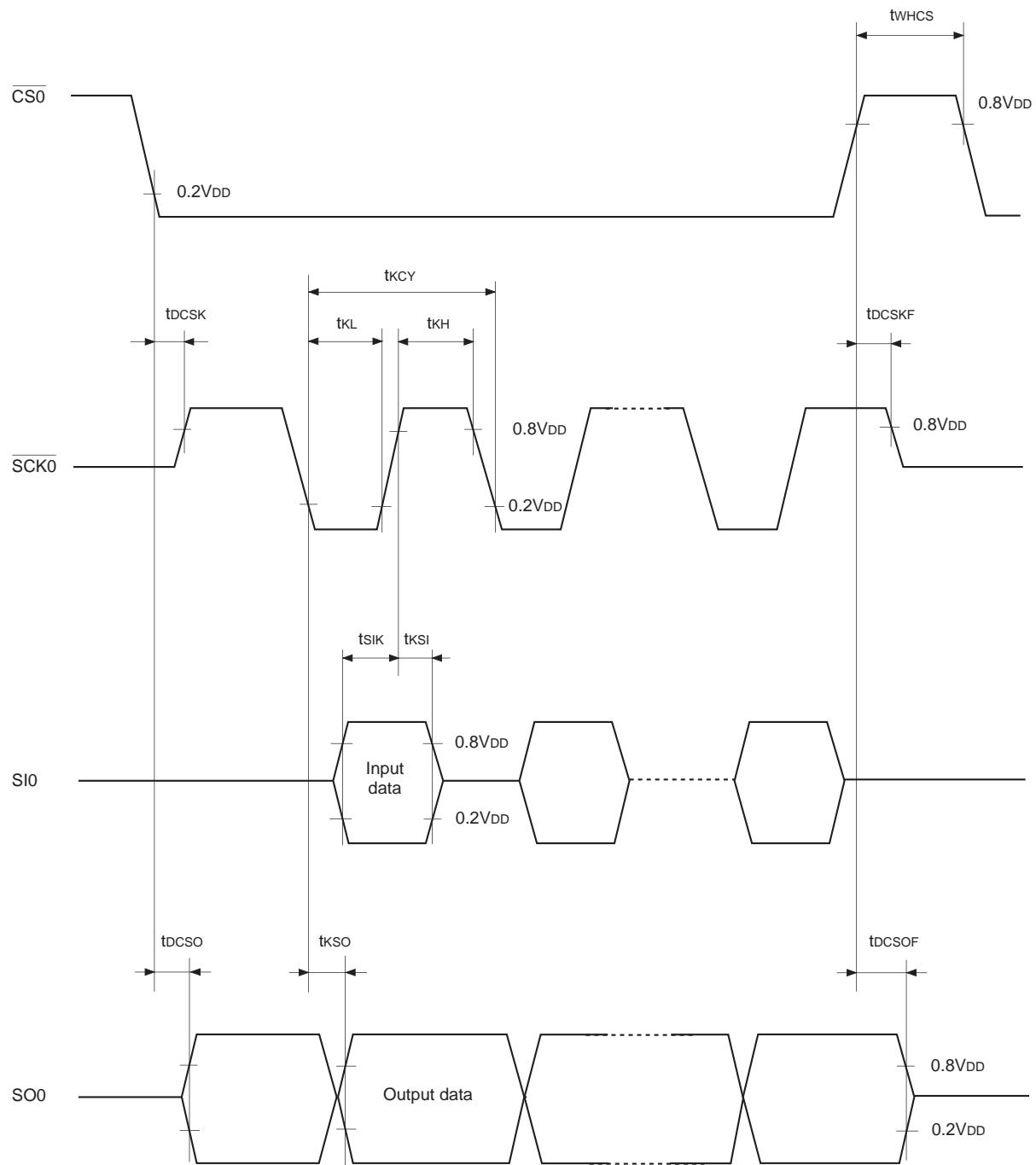
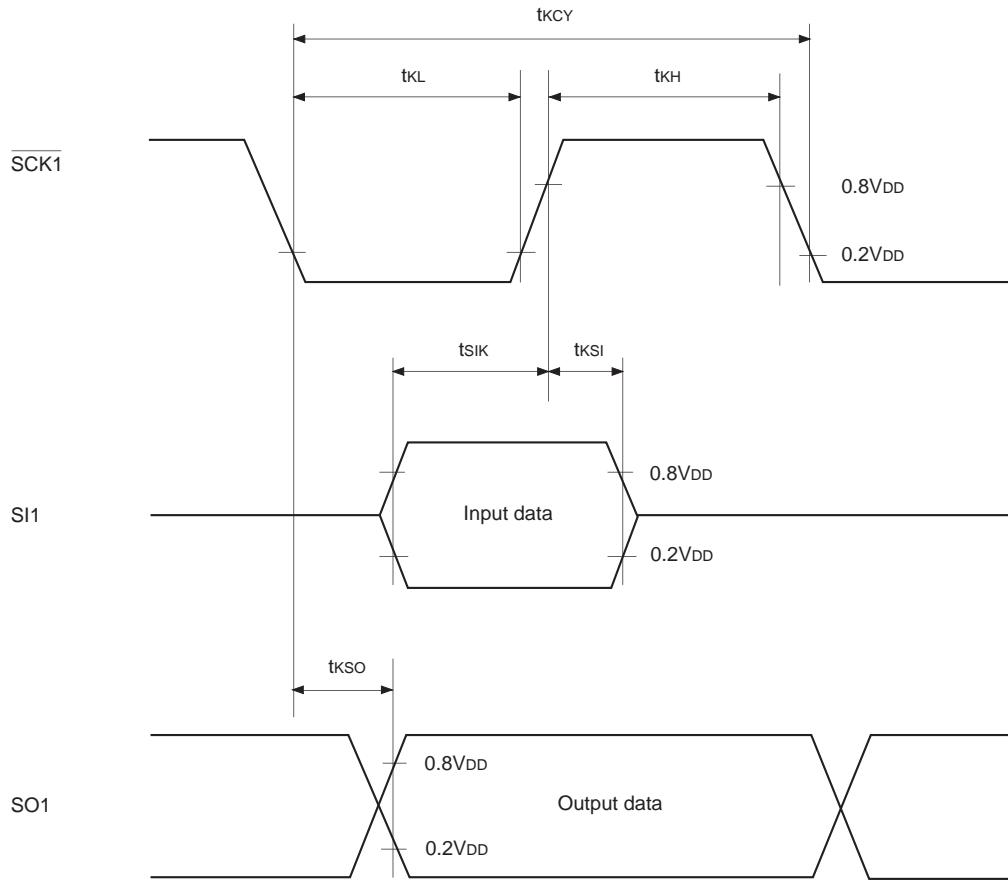


Fig. 4. Serial transfer CH0 timing

Serial transfer (CH1)(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V reference)

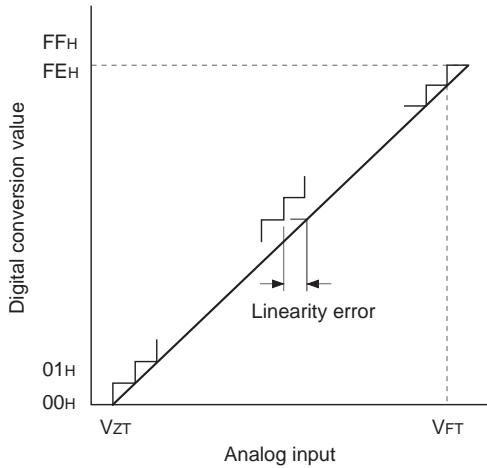
Item	Symbol	Pin	Condition	Min.	Max.	Unit
SCK1 cycle time	t _{KCY}	SCK1	Input mode	1000		ns
			Output mode	16000/f _C		ns
SCK1 High, Low level width	t _{KL} , t _{KH}	SCK1	Input mode	400		ns
			Output mode	8000/f _C – 50		ns
SI1 input setup time (for SCK1 ↑)	t _{SIK}	SI1	SCK1 input mode	100		ns
			SCK1 output mode	200		ns
SI1 input hold time (for SCK1 ↑)	t _{KSI}	SI1	SCK1 input mode	200		ns
			SCK1 output mode	100		ns
SCK1 ↓ → SO1 delay time	t _{KSO}	SO1	SCK1 input mode		200	ns
			SCK1 output mode		100	ns

Note) The load condition for the SCK1 output mode, SO1 output delay time is 50pF + 1TTL.**Fig. 5. Serial transfer CH1 timing**

(3) A/D converter characteristics

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, AVREF = 4.0 to AVDD, Vss = AVss = 0V reference)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error						± 5	LSB
Zero transition voltage	VZT ^{*1}		Ta = 25°C VDD = 5.0V Vss = AVss = 0V	-10	70	150	mV
Full-scale transition voltage	VFT ^{*2}			4930	5050	5120	mV
Conversion time	tCONV			160/fADC ^{*3}			μs
Sampling time	tSAMP			12/fADC ^{*3}			μs
Reference input voltage	AVREF	AVREF		VDD - 0.5		VDD	V
Analog input voltage	VIAN	AN0 to AN7		0		AVREF	V
AVREF current	IREF	AVREF	Operation mode		0.6	1.0	mA
	IREFS		Sleep mode Stop mode 32kHz operation mode			10	μA



*1 VZT : Value at which the digital conversion value changes from 00H to 01H and vice versa.

*2 VFT : Value at which the digital conversion value changes from FEH to FFH and vice versa.

*3 fADC indicates the below values due to ADC operation clock selection.
During PS2 selection, fADC = fc/2
During PS1 selection, fADC = fc

Fig. 6. Definition of A/D converter terms

(4) Interruption, reset input (Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{ss} = 0V reference)

Item	Symbol	Pins	Condition	Min.	Max.	Unit
External interruption High, Low level width	t _{IH} t _{IL}	INT0 INT1 INT2 INT3 NMI PJ0 to PJ7		1		μs
Reset input Low level width	t _{RSL}	<u>RST</u>		8/fc		μs

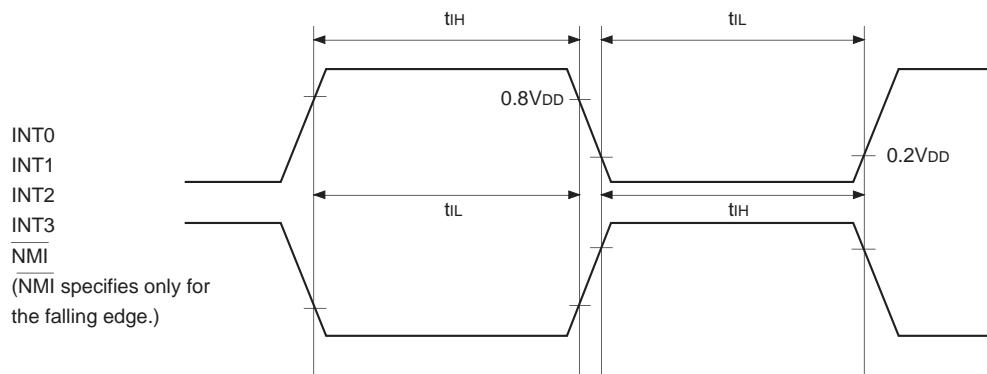
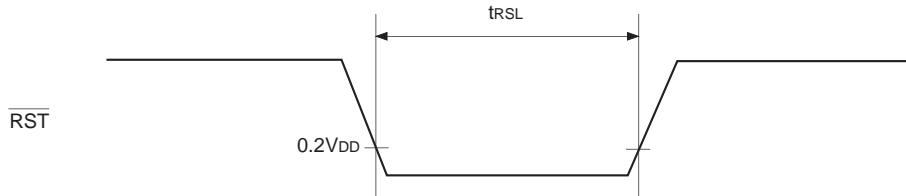


Fig. 7. Interruption input timing

Fig. 8. RST input timing

Appendix

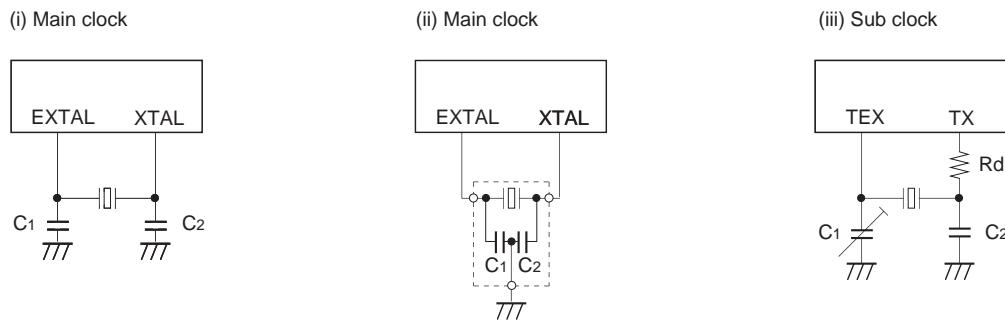


Fig. 9. SPC700 series recommended oscillation circuit

Manufacturer	Model	fc (MHz)	C1 (pF)	C2 (pF)	Circuit example
MURATA MFG CO., LTD.	CSA4.19MG	4.19	30	30	(i)
	CSA8.00MG	8.00			
	CSA10.0MT	10.00			
	CST4.19MGW*	4.19			(ii)
	CST8.00MTW*	8.00			
	CST10.00MTW*	10.00			
RIVER ELETEC CORPORATION	HC-49/U03	4.19	15	15	(i)
		8.00			
		10.00			
KINSEKI LTD.	HC-49/U (-S)	4.19	27	27	(i)
		8.00			
		10.00			

Those marked with an asterisk (*) signify types with built-in ground capacitance (C1, C2).

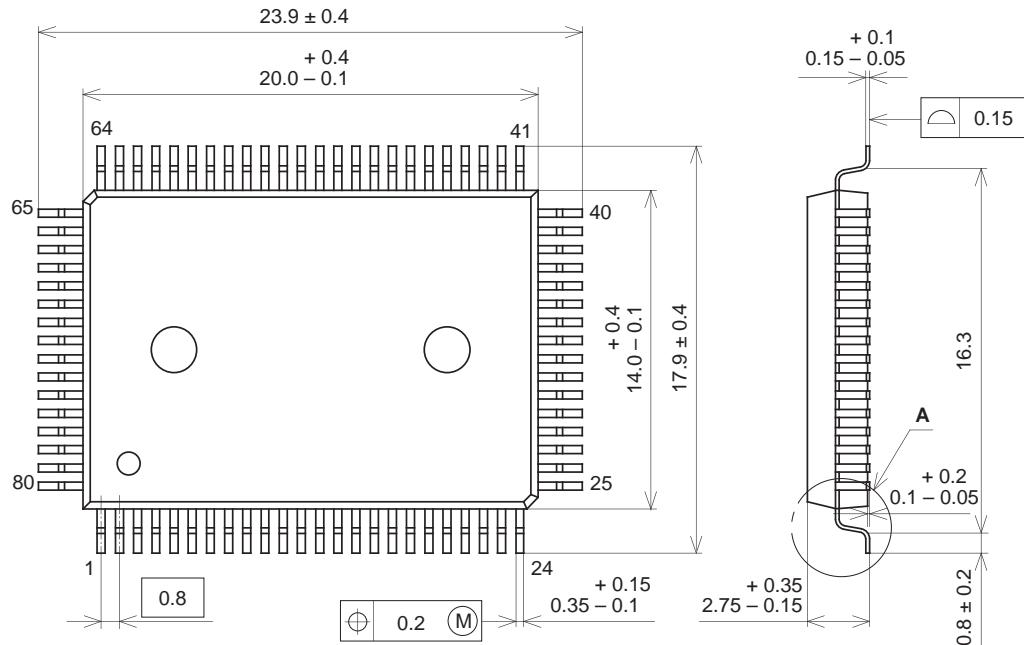
Mask option table

Item	Content	
Reset pin pull-up resistance	Non-existent	Existent

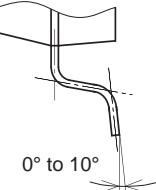
Package Outline

Unit: mm

80PIN QFP (PLASTIC)



DETAIL A



PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.6g

SONY CODE	QFP-80P-L01
EIAJ CODE	QFP080-P-1420
JEDEC CODE	-----